

### 一级代理商：

深圳市弗瑞鑫电子有限公司

地址：深圳市宝安区西乡大道302号金源商务大厦B座三楼

0 -  
0 - 0 0

.frxelec.



5. Ab ol e Ma im m Ra ing (Ta=25 )

| Pa ame e | S mbol                    | Ra ed Val e | Uni |
|----------|---------------------------|-------------|-----|
|          |                           | 0           |     |
|          |                           | 1           |     |
|          |                           | 100         |     |
|          |                           | 00          |     |
|          |                           | 00          |     |
|          | ( )                       | 100         | ( ) |
|          | ( 1 10 )                  | 1           |     |
|          |                           | 1           |     |
|          |                           | 00          |     |
|          |                           | 0           |     |
|          |                           | 0           |     |
|          |                           | - 0 + 110   |     |
|          |                           | - + 1       |     |
|          | (□)                       |             |     |
| □ *1     | 1 □                       |             |     |
| * 10     | , . . . 0 0% . . . , 1, & |             |     |
|          |                           |             |     |

Temperatura Ta=25 C

| Simbol | Min | T   | Ma  | Uni | Condi ion |
|--------|-----|-----|-----|-----|-----------|
|        | --- | 1.  | 1.  |     | 10        |
|        | --- | --- |     |     |           |
|        | --- | 10  | 100 |     |           |
|        | --- | --- |     |     | 100       |
| - 0    | --- | 10  | --- | /   | 0         |
| - 0    | --- | 00  | --- |     |           |

01000M

7. O de Info ma ion

Pa N mbe

**OR-M302X-W-Y-Z**

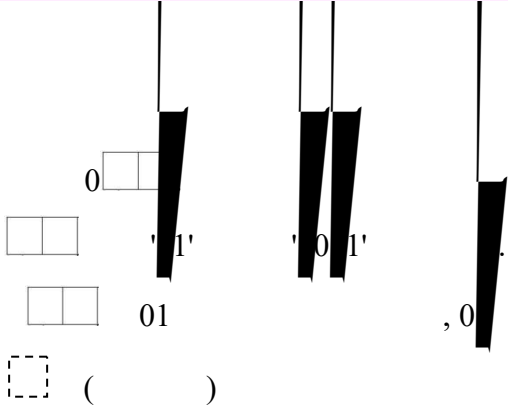
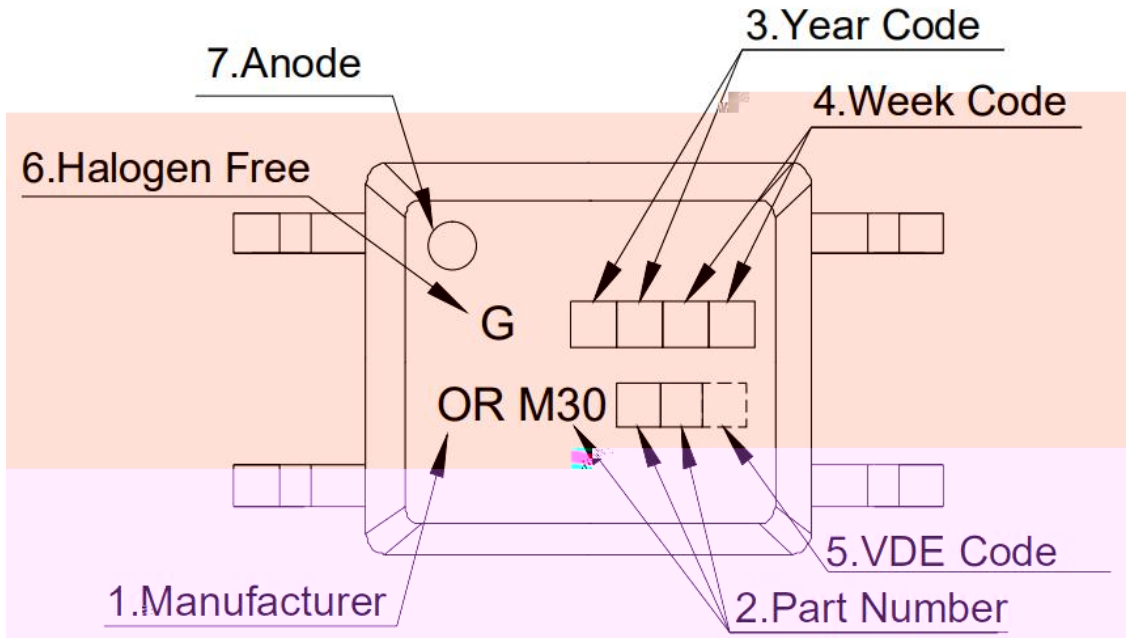
**O OR-M305X-W-Y-Z**

No e

(0,1, )  
 ( 1).  
 ( ).  
 .  
 \*

| O ion | De c i ion | Packing an i |
|-------|------------|--------------|
|       | ( )+ &     | 000          |
| 1     | ( )+ 1 &   | 000          |

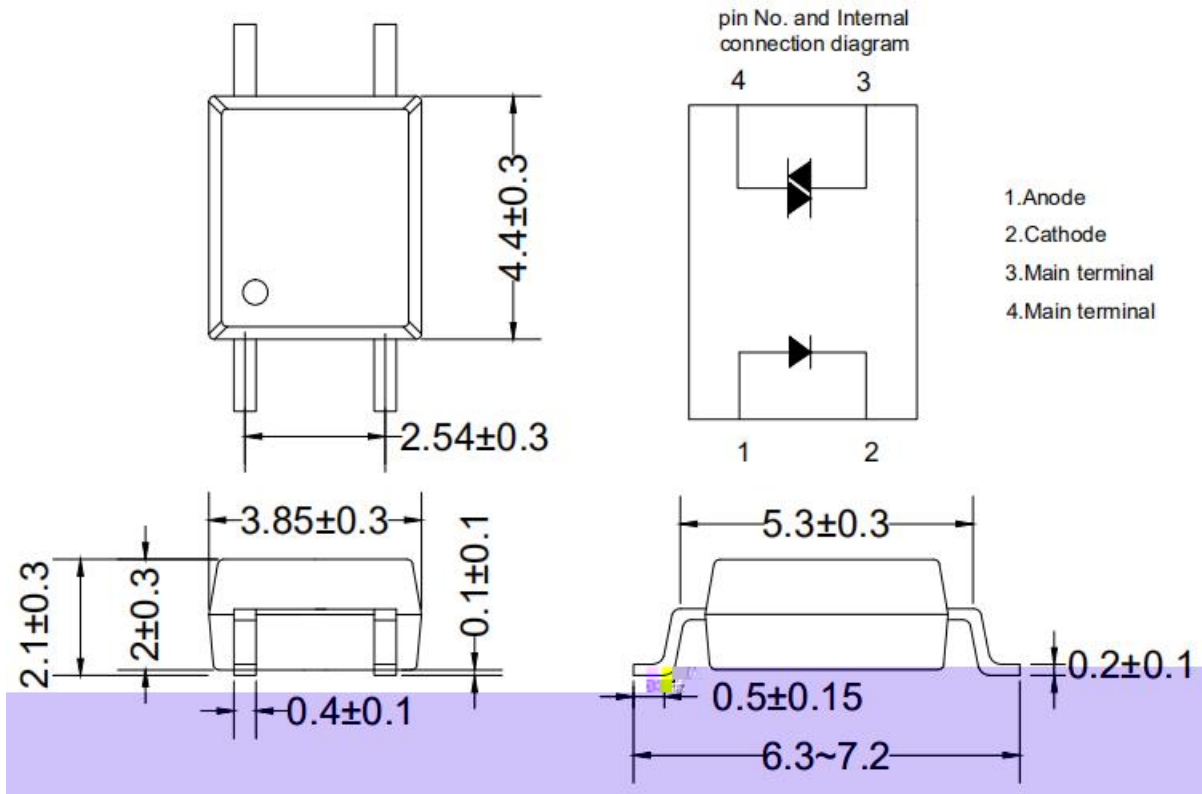
### 8. Naming Rule



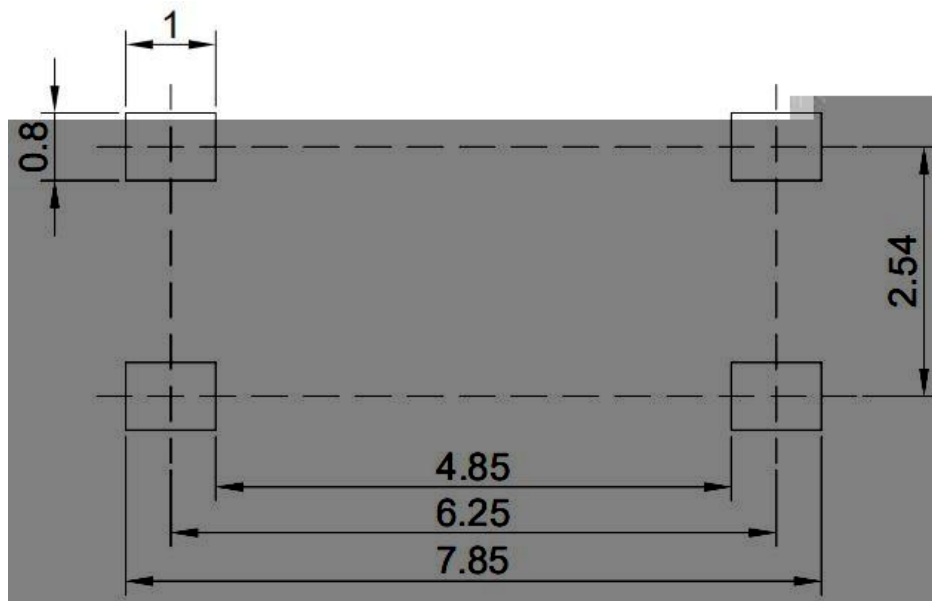
\*

### 9. Package Dimension

- 0



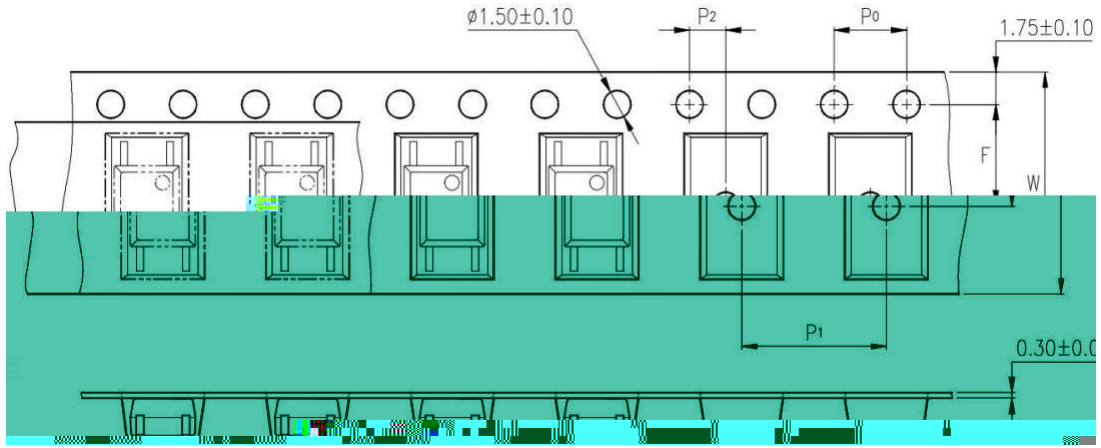
### 10. Recommended Foot Print Pattern (Mo n Pad)



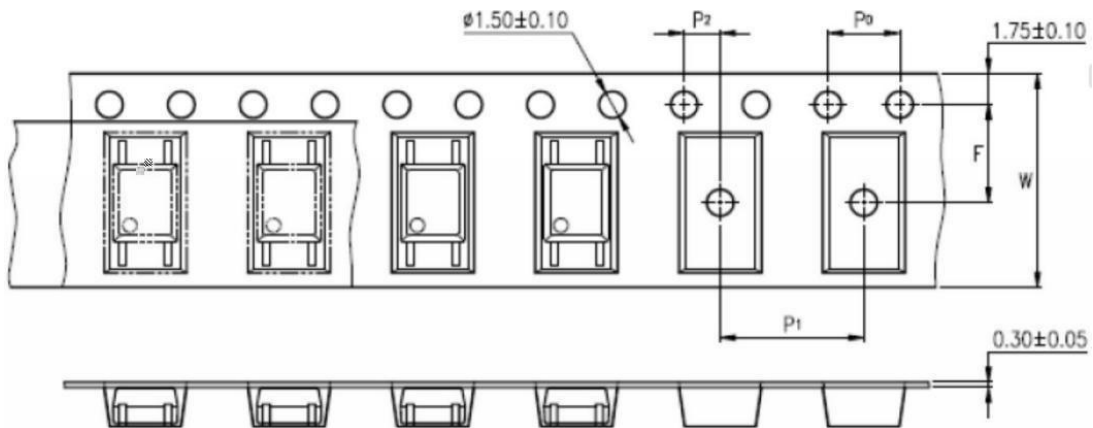
ni mm

### 11. Ta ing Dimen ion

(1) - 0 -



( ) - 0 - 1



|  |   |            |
|--|---|------------|
|  |   | ( )        |
|  |   | 1 0. 0. 1  |
|  | 0 | 0.1 0.1    |
|  |   | . 0.1 0. 1 |
|  | 1 | 1 0.1 0.0  |
|  |   | 0.1 0. 1   |

|     |     |
|-----|-----|
|     | / 1 |
| ( ) | 000 |

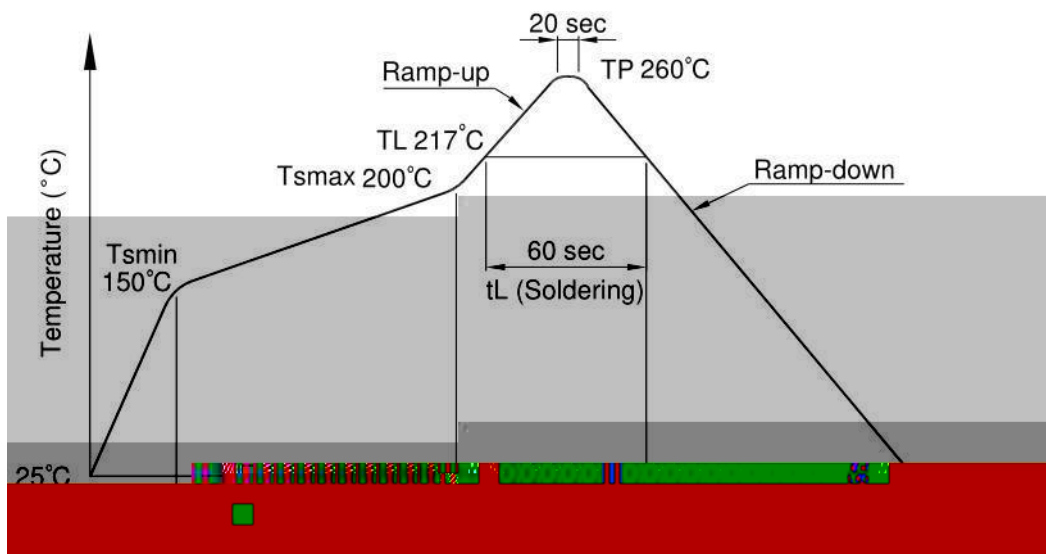




### 13. Temperature Profile Of Soldering

1 ( - -0 0 )

| Profile item | Condition |
|--------------|-----------|
| - ( )        | 0         |
| - ( )        | 00        |
| - ( ) ( )    | 0 0       |
| - ( )        | 1         |
| - ( )        | 0         |
|              | 0         |
|              | 0         |
| -            | /         |
| -            | /         |
|              |           |



( 111 )

|  |             |
|--|-------------|
|  | 0+0/-<br>10 |
|  | 1 0<br>0 0  |



|  |  |
|--|--|
|  |  |
|--|--|

### 14. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward current vs Ambient temperature

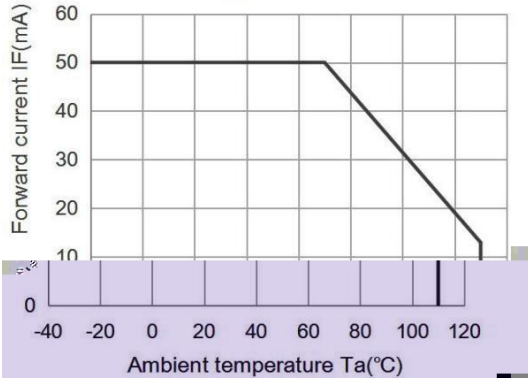


Fig.2 On-state current ITM (A) vs Ambient temperature

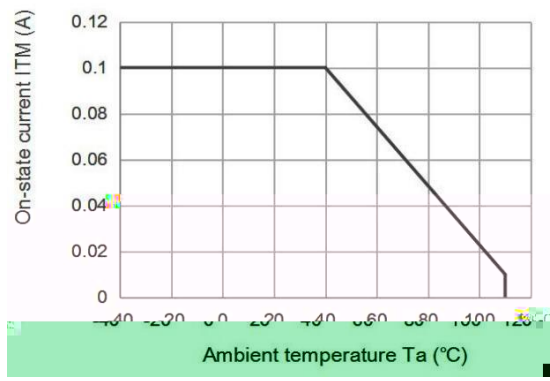


Fig.3 Minimum Trigger Current vs. Ambient temperature

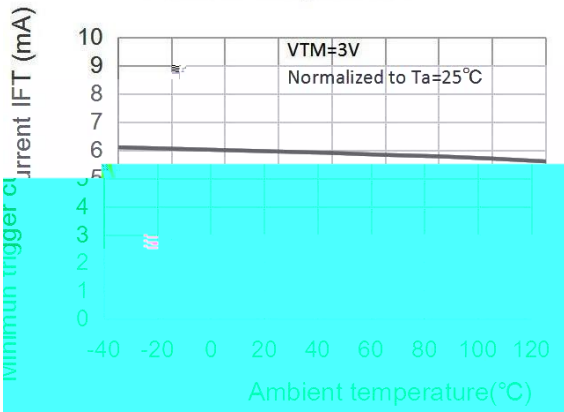


Fig.4 Forward current vs. Forward voltage

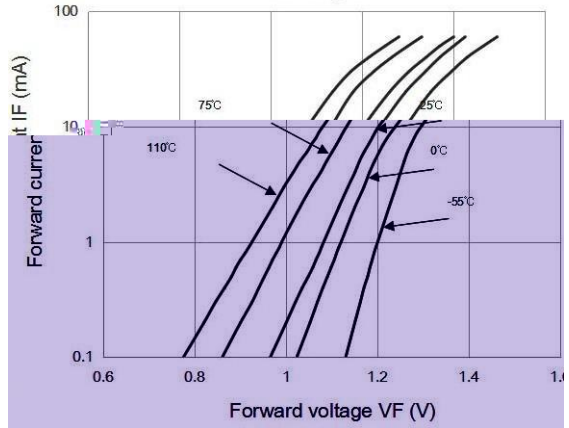


Fig.5 On-state voltage vs. Ambient temperature

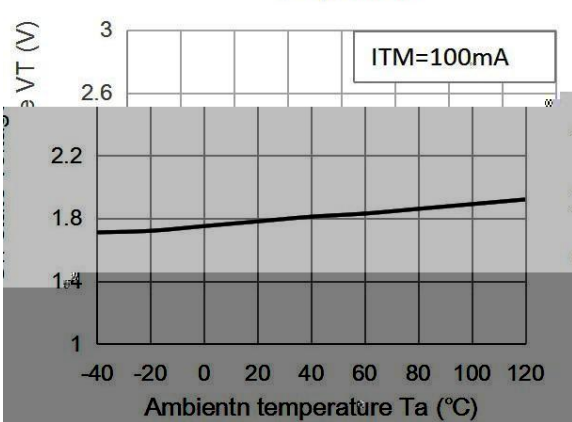


Fig.6 Holding current vs. Ambient temperature

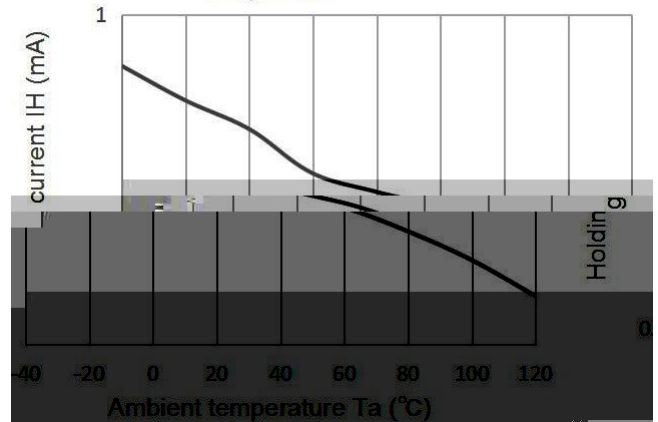


Fig.7 Repetitive peak off-state current vs. Temperature

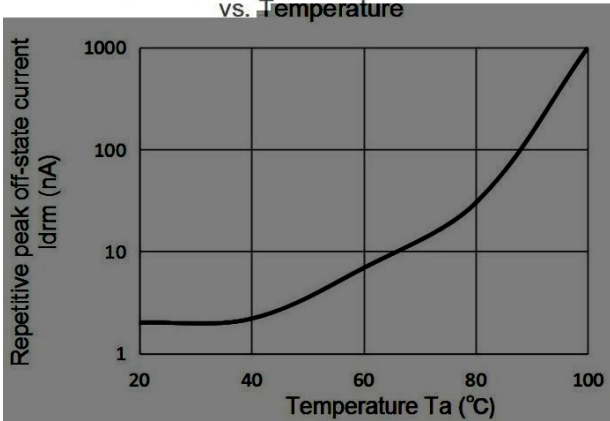
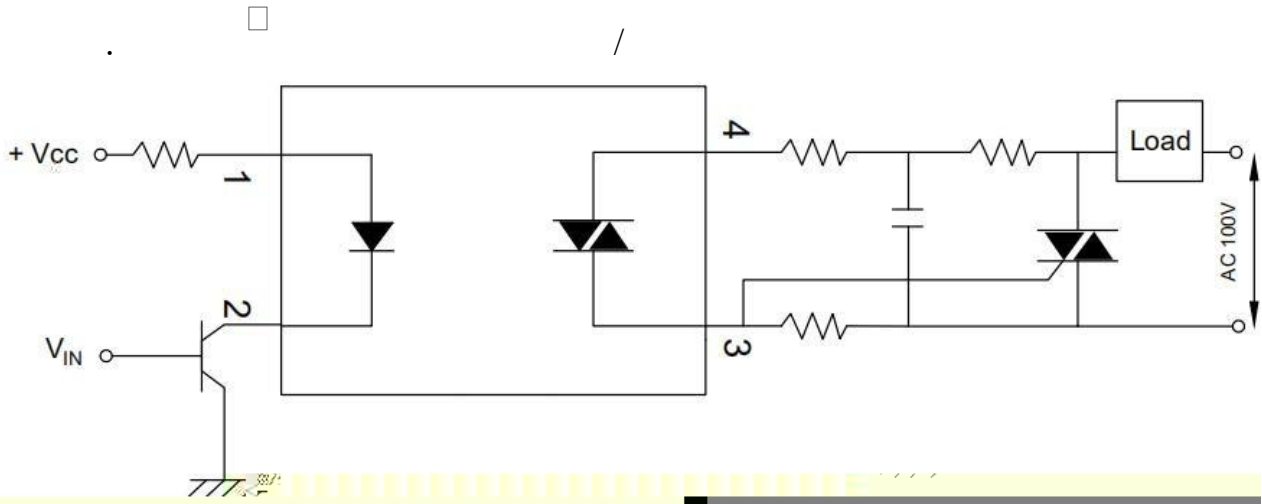
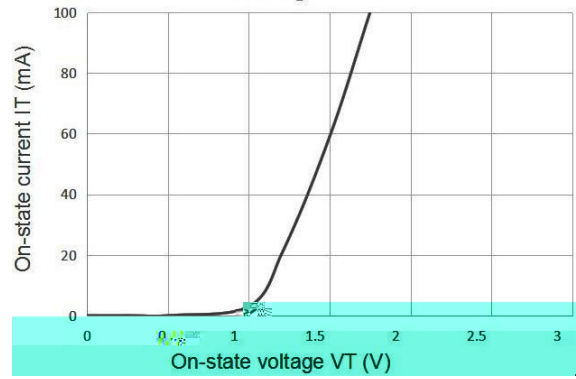
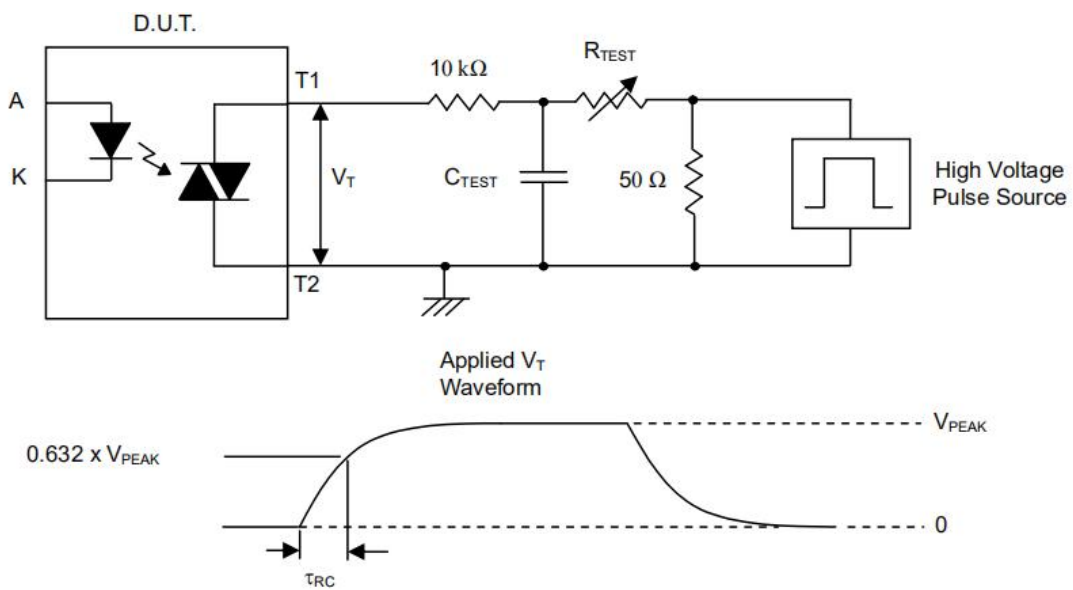


Fig.8 On-state current vs. On-state voltage



10. / &



## Measurement Method

The high voltage pulse is set to the required  $V_{PEAK}$  value and applied to the D.U.T. output side through the RC circuit above. LED current is not applied. The waveform  $V_T$  is monitored using a x100 scope probe. By varying  $R_{TEST}$ , the  $dv/dt$  (slope) is increased, until the D.U.T. is observed to trigger (waveform collapses). The  $dv/dt$  is then decreased until the D.U.T. stops triggering. At this point,  $\tau_{RC}$  is recorded and the  $dv/dt$  calculated.

$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

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For example,  $V_{PEAK} = 600V$  for EL306X series. The  $dv/dt$  value is calculated as follows:

$$dv/dt = \frac{0.63 \times 600}{\tau_{RC}} = \frac{378}{\tau_{RC}}$$